

### 1. Features

- 1) High common mode impedance at high frequency effects excellent noise suppression performance.
- 2) FDCW3216series realizes small size and low profile 3.2\*1.6\*1.8 mm.
- 3) 100% Lead (Pb) & Halogen-Free and RoHS compliant.

# 2. Applications

- Power switch and servers.
- USB communication.
- Telecommunication applications.
- Panel link for LCD panels.
- Countering common mode noise affecting signals in high-speed lines.

### 3. Product Identification



- ① FDCW \_\_\_\_\_ Series name
- (2)3216 ----- Dimension
- 2 3 ----- 2 lines
- **④ 600** ----- Common Mode Impedance  $(\Omega)$
- Т ----- Packing(Tape & Reel) (5)
- HSF Products(Hazardous Substance Free Products) (6)F -----

#### 4. Dimensions (unit:mm)





**Recommend Land Pattern** 

	А	В	С	D	E
	3.20±0.20	1.60±0.20	1.80±0.20	0.6TYP	0.6TYP
L					





### 5. Structure and Components

No	Part Name	Material Name		
1	Lid	Ni-Zn Ferrite		
2	Epoxy	Epoxy resin		
3	Wire	Enameled copper wire		
(4)	Core	Ni-Zn Ferrite		
6	Electrode	Ag+Ni+Sp ploting		
(5)	structure	Ag+Ni+Sn plating		



# 6. Chematic Diagram



# 7. MEASURING CIRCUITS 2LINE

1) Common mode:



2) Differential mode:





### **8.Electrical Characteristics**

	Z (共模阻抗) @100MHZ	DCR	IR	Rated Voltage (Vdc)	Rated Current
品名	Ω	mΩ	MΩ	V	mA
	±25%	MAX	MIN	/	MAX
FDCW3216-2-500TF	50	250	10	50	400
FDCW3216-2-900TF	90	300	10	50	370
FDCW3216-2-161TF	160	400	10	50	340
FDCW3216-2-261TF	260	500	10	50	310
FDCW3216-2-601TF	600	800	10	50	260
FDCW3216-2-102TF	1000	1000	10	50	230
FDCW3216-2-222TF	2200	1200	10	50	200

#### Notes

- 1. All test data is referenced to 25 °C ambient
- 2. Operating temperature range 40 °C to + 125 °C
- 3. Irms (A):DC current (A) that will cause an approximate  $\Delta T$  of 40 °C(reference ambient temperature is 25 °C)
- 4. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

## 9. Typical impedance vs. frequency





# 10. Reliability Test

Items	Requirements	Test Methods and Remarks
Resistance to	1. No visible mechanical damage	1. Solder on PCB to Reflow test Peak Temp. 260 $\pm5^{\circ}$ C 5 $\sim$ 10
Soldering Heat	2. Impedance change: Within $\pm$ 20%	secs ,Cycles :2 timesRe-flowing Profile: Please refer to Fig-1
		2. Test board thickness: 1.5mm
		3. Test board material: glass epoxy resin
		4. The specimen shall be stored at standard atmospheric
		conditions for 1 hour, after which the measurement shall be
		made.product showed no damage under microscope.
		Fig-1
		260°C 217°C 217°C Max Ramp Up Rate=3°C/sec. Max Ramp Down Rate=6°C/sec 150°C 25°C Time 25°C to Peak =8 min max
High	1. No visible mechanical damage	1. Temperature: 125±2℃
Temperature	2. Impedance change: Within $\pm$ 20%	2. Duration: 1000 hours
		The specimen shall be stored at standard atmospheric
		conditions for 1 hour, after which the measurement
		shall be made.
Steady	1. No visible mechanical damage	1. Temperature:85℃
damp-heat	2. Impedance change: Within $\pm$ 20%	2. Humidity: 85% RH
		3. Duration:1000 hours
		4. The specimen shall be stored at standard
		atmospheric conditions for 1 hour, after which the
		measurement shall be made.
Mechanical	1.No visible mechanical damage	1.Frequency: 10HZ~55HZ~10HZ/Min Cycles
Vibration	2.Impedance change: Within $\pm$ 20%	2.Amplitude: 1.5 mm
		3.Directions: X,Y,Z
		4.Time: 2 hours in each directions (total of 6 hours)



# Specifications for Wire Wound Chip Common Mode Choke Coil

Items	Requirements	Test Methods and Remarks
Thermal Shock	1.No visible mechanical damage 2.Impedance change: Within $\pm$ 20%	1. Temperature and time: -40 °C for 30±3 min→125 °C for 30±3min, please refer to Fig-2 2. Transforming interval: Max. 3 Min 3. Tested cycle: 1000 cycles 4. The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made. 125°C 30±3min Ambient Temperature 40°C Fig-2 3 Min (max.)
Salt Spray	1.No visible mechanical damage 2.Impedance change: Within $\pm$ 20%	<ol> <li>Salt concentration: (5 ± 1)% (mass percent)</li> <li>pH value:6.5 - 7.2</li> <li>temperature: 35 ± 2 °C</li> <li>humidity: 85%</li> <li>time: 24 hours</li> <li>in normal temperature and humidity for 1 ~ 2 hours, testing inductance, the inductance value change can not be more than before test ± 10%.</li> </ol>
Terminal strength	No visible mechanical damage	<ol> <li>The electrode of the inductor is soldered to the PCB, to Fig-3 Then apply a force in the direction o the arrow.</li> <li>8N force.</li> <li>Keep time: 10(±1)s</li> <li>The first three tests were OK, and the force was applied until the peak value of the product peeling. The test speed was set in the range of 3 ~ 8mm/min.</li> </ol> Fig-3 Fig-3 Pressure Product Test board fixture



### 11. Packaging Information

### 1) Tape Packaging Dimensions (Unit: mm)



Туре	W	PI	AO	BO	KO	t	E	F	P2	DO	DI	PO
FDCW	8.00	4.00	1.90	3.60	1.95	0.25	1.75	3.50	2.00	1.55	1.00	4.00
3216	±0.10	±0.10	±0.10	±0.10	±0.10	$\pm 0.05$	±0.10	±0.10	$\pm 0.10$	$\pm 0.05$	±0.10	±0.10





### 3) Taping Drawings





4) Reel Dimensions (Unit: mm)



A (mm)	9.50±1.0
B (mm)	60.0±1.0
C (mm)	13.0±0.2
D (mm)	178.0±1.0

### 5) Packaging Quantity(PCS)

Turno	Standard Quantity					
Туре	Reel	Inner box	Carton box			
FDCW3216	2000 pcs / reel	5Reel / box (10000 pcs)	10 Middle boxes, (100000 pcs)			

### 6) Peel force of top cover tape

The peel speed shall be about 300mm/minute.

The peel force of top cover tape shall be between 10 to 100gf.





### 7) Reel Label

- Label on the reel
  - Customer's part Number
  - Lot Number
  - Quantity
  - date code
- Shipping Label
  - Customer's part Number
  - Manufacturer's part Number
  - Quantity
  - date code

#### 8) Inner Box



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Packaging Type	A (mm)	B (mm)	C (mm)
Inner box	188	195	67

### 9) Carton

